Amendments to the Specification:

Please replace the paragraph beginning at page 1, line 4, with the following rewritten paragraph:

– The present invention relates to an integrated circuit package having a resistant layer for stopping flowed gluecentral leads, and more particularly to an integrated circuit package which may be conveniently manufactured with reduced manufacturing costs. –

Please replace the two paragraphs beginning at page 1, line 8, with the following rewritten paragraphs:

– Referring to FIG. 1, a conventional integrated circuit package having central leads includes a substrate 10, a glue layer 12, an integrated circuit 14, a plurality of wires 16, and a compound layer_18. The substrate 10 has an upper surface 20, a lower surface_22 and a long slot_24 penetrating from the upper surface_20 to the lower surface_22, wherein the lower surface_22 of the substrate 10 is formed with wiring regions_26 arranged at the two sides of the long slot_24, and the wiring region_26 is formed with connected connection points_28. The glue layer_12 is coated on the upper surface_20 of the substrate_10, and is located at the periphery of the long slot_24. The integrated circuit 14 has a first surface_30 and a second surface_32, wherein the central portion of the first surface_30 of the integrated circuit 14 is formed with bonding pads_34, while the first surface_30 of the substrate_10 is adhered to the glue layer_12, so that as to the bonding pads_34 of the substrate_10 are exposed from the long slot24 slot 24. The wires are arranged within the long slot_24 of the substrate_10, and are electrically connected the bonding pads_34 of the integrated circuit_14 to the connected connection points_28 of the substrate_10.The compound layer_18 is filled within the long slot 24 for protectingto protect the wires.

However, the above-mentioned integrated circuit image package has the following drawbacks. When the glue layer_12 is coated on the upper surface_20 of the substrate_10, the flowed glue of the glue layer_12 is covered on covers the wiring region_26 through the long slot_24 of the substrate_10, so that the connected

connection points 28, which are arranged at the wiring region 26, are covered by the flowed glue. –

Please replace the four paragraphs beginning at page 2, line 9, with the following rewritten paragraphs:

– An object of the present invention is to provide an integrated circuit package, which is capable of preventing the flowed glue of the glue layer from ~~covered~~ covering the wiring region, so that the wire bonding is easy.

Another object of the present invention is to provide an integrated circuit package ~~having central leads~~, which may be conveniently manufactured with reduced manufacturing costs.

To achieve the above-mentioned objects, the present invention provides an integrated circuit package ~~having central leads includes~~ including a substrate, a glue layer, an integrated circuit, a plurality of wires, and a first compound layer. The substrate has an upper surface, a lower surface, and ~~,and~~ a long slot penetrating from the upper surface to the lower surface, wherein the lower surface is ~~forming~~ formed with wiring regions arranged at ~~the~~ two sides of the long slot, and the wiring regions are ~~forming~~ formed with a plurality of ~~connected~~ connection points. The resistant layer is coated on and in contact with the lower surface of the substrate, and is located between the long slot and the wiring region. The glue layer is coated on the upper surface of the substrate and arranged at the periphery of the long slot. The integrated circuit has a first surface ~~forming~~ formed with a plurality of bonding pads and a second surface, wherein the first surface is adhered to the glue layer, ~~then~~ and the bonding pads are exposed from the long slot of the substrate. The wires, each of which is arranged within the long slot of the substrate, ~~and is~~ electrically ~~connected~~ connect the bonding pads of the integrated circuit to the ~~connected~~ connection points of the substrate, respectively. The first compound layer is filled within the long slot of the substrate ~~for~~ to protecting the ~~each~~ wires.

Utilizing the resistant layer to prevent the flowed glue from covering the ~~covered yje connected~~ connection points may easily achieve the objects and

functions of the invention. –

Please replace the two paragraphs beginning at page 3, line 14, with the following rewritten paragraphs:

– FIG. 2 is a cross-sectional view showing an integrated circuit package ~~having central leads~~ of the present invention.

FIG. 3 is a top-view ~~of~~ showing the substrate of the present invention. –

Please replace the eight paragraphs beginning at page 3, line 18, with the following rewritten paragraphs:

– Referring to FIG. 2, an integrated circuit package ~~having central leads~~ of the present invention includes a substrate_40, a resistant layer_42, a glue layer_44, an integrated circuit_46, a plurality of wires_47, a first compound layer_48, and a second compound layer_50.

The substrate_40 has an upper surface_52, a lower surface_54, and a long slot 56 penetrating from the upper surface_52 to the lower surface_54. The lower surface_54 of the substrate_40 is formed with wiring regions_58 arranged at the two sides of the long slot_56, and the wiring regions_58 are formed with a plurality of ~~connected~~ connection points_60, ~~each of~~ which ~~is~~ are formed with a ball grid array. Please ~~refer~~ring to FIG._3, the length of the wiring region ~~60~~ 58 is shorter than that of the long slot_56 of the substrate_40. Therefore, while the long slot_56 of the substrate is drilled, the periphery of the long slot_56 may be cracked, ~~so that~~ and the flowed glue of the glue layer_44 can not flow to the wiring regions_58 via the cracked according to the resistant layer 42. The resistant layer 42 separates the long slot 56 from the wiring region 58. A length of the resistant layer 42 is substantially equal to the length of the wiring region 58.

The resistant layer_42 is coated on the lower surface_54 of the substrate_40, and is located between the long slot_56 and the wiring region_58. In ~~preferred~~ the embodiment, the resistant layer_42 is made of green.

The glue layer_44 is coated on the upper surface_52 of the substrate_40, and is located at the periphery of the long slot_56.

The integrated circuit_46 has a first surface_62 on which a plurality of bonding pads_66 are formed, and a second surface_64. The first surface_62 is adhered to the glue layer_44, ~~thus,~~ and the bonding pads_66 are exposed from the long slot_56 of the substrate_40.

The plurality of wires_47, each of which is arranged within the long slot_56 of the substrate_40, ~~and is~~ electrically connected the bonding pads_66 of the integrated circuit_46 to the ~~connected~~ connection points_60 of the substrate_40.

The first compound layer_48 is filled within the long slot_56 of the substrate 40 ~~for protecting~~to protect ~~the~~ each wire_47~~, respectively~~.

The second compound layer_50 is covered on the upper surface_52 of the substrate_40 to ~~prevent~~ protect the integrated circuit_46. --

Please replace the two paragraphs beginning at page 5, line 6, with the following rewritten paragraphs:

-- 1. Since ~~if~~ the flowed glue of the glue layer_44 ~~is flowed~~ flows to the lower surface_54 of the substrate_40 through the long slot_56, the resistant layer_42 prevents the flowed glue ~~can be prevented by the resistant layer42 to~~ from flowing to the wiring regions_58, so that the ~~connected~~ connection points_60 ~~may not~~ cannot be covered by the flowed glue.

2. ~~Since t~~The length of each of the wiring regions_58 ~~are~~ is shorter than that of the long slot_56~~, so that, while drilled the long slot56, So,~~ if the substrate_40 is cracked while the long slot_56 is being drilled, ~~which is can be not coupled to the wiring regions58, thus the connected~~ the connection points_60 can be not covered by the flowed flue of the glue layer_44. --